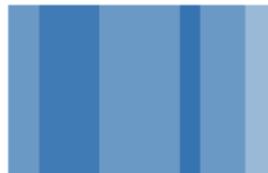


# EPOXONIC® 375



**Flexible potting compound  
for Automotive Engineering,  
Microelectronics and Electrical Engineering**

EPOXONIC® 375 is a solvent-free, mineral filled 2-part potting compound based on epoxy resin.

## Main characteristics:

Heat resistance to 150 °C

Thermal shock resistance

Flexibility

Long pot life

## Application:

EPOXONIC® 375 is especially suited for low stress potting of pressure sensitive electrical devices with high requirements for thermal shock resistance.

## Properties:

Specific values measured by standard test specimen at 23 °C, cured 2 h / 120 °C.

|   |   |                    |
|---|---|--------------------|
| Operating temperature <sup>1)</sup>         | -40 °C to +150 °C                             |                    |
| Colour                                      | black   |                    |
| Shore hardness                              | 87 Shore A                                    | DIN EN ISO 868     |
| Density                                     | approx. 1.7 g/cm <sup>3</sup>                 | DIN 66137-3        |
| Glass transition temperature                | -40 °C to -30 °C                              | DIN EN ISO 11357-2 |
| Coefficient of linear thermal expansion CTE | 130 – 140 × 10 <sup>-6</sup> /K (50 – 100 °C) | ISO 11359-2        |
| Tensile strength                            | 13 MPa  | DIN EN ISO 527     |
| Elongation at break                         | 55 %  | DIN EN ISO 527     |
| E-modulus                                   | 40 MPa  | DIN EN ISO 527     |

1) Depending on the application, other temperature limits may be reasonable

## Processing:

|                                    |  |                                   |  |  |  |  |  |  |  |
|------------------------------------|--|-----------------------------------|--|--|--|--|--|--|--|
| Mix ratio                          | Part A : Part B = 100 : 120 parts by weight  |                                   |  |  |  |  |  |  |  |
| Viscosity<br>cone/plate viscometer |  |                                   |  |  |  |  |  |  |  |
|                                    | 25 °C  | 50 – 60 Pas (Part A)              |  |  |  |  |  |  |  |
|                                    | 25 °C  | 75 – 85 Pas (Part B)              |  |  |  |  |  |  |  |
|                                    | 25 °C  | 60 – 70 Pas (Mixture A + B)       |  |  |  |  |  |  |  |
|                                    | 35 °C  | 25 – 30 Pas (Mixture A + B)       |  |  |  |  |  |  |  |
|                                    | 60 °C  | 1500 – 2000 mPas (Mixture A + B)  |  |  |  |  |  |  |  |
| Pot life                           | 25 °C  | > 20 h (time to double viscosity) |  |  |  |  |  |  |  |
| Method of application              | e.g. dispenser   |                                   |  |  |  |  |  |  |  |
| Cure schedule                      | e.g. 2 h / 120 °C<br>Optimum cure schedules have to be determined by the specific application. |                                   |  |  |  |  |  |  |  |

## Storage:

The shelf life of EPOXONIC® 375 Part A and Part B is 6 months at temperatures < 25 °C when stored in tightly closed, original containers. Part A and Part B have to be stirred very well before use. Partly emptied containers should be tightly closed immediately after use.

## Packaging:

EPOXONIC® 375 Part A and Part B are delivered in metal cans. Other packaging options are available upon request.

## Health and Safety:

Recommended industrial hygiene procedures should always be followed when handling this product. Please refer to the corresponding Material Safety Data Sheet for details.

## Quality Assurance:

If required EPOXONIC® 375 will be supplied with a Certificate of Analysis.

## Disclaimer:

All information herein is based on the present state of knowledge and believed to be reliable. Any suggestions or recommendations are made without liability on our part since we shall have no control over the use of our product. Buyers and users should make their own assessment of this product under their own conditions and for their own requirements.